micross
one source. one solution.™

Extending the Lifecycle of Your Products
EOL Die Sustainment Program - EDSP

Customers need electronic components to be available in support of their products for the entirety of the life cycle. Micross' decades of proven success, unparalleled knowledge & extensive capabilities can extend the life cycle of products for critical customer needs.

When customers require a specific form fit function component that is no longer supported or will become obsolete, Micross can provide a solution that will meet the original specification, steering clear of expensive requalification costs. Where no alternate is available, Micross stands ready to assist with the challenge at hand.

Targeted support and customizable scalable solutions allow our suppliers to protect their brand & revenue on intended phase out products. Providing an avenue for die sustainment to key customers with their most pressing product & manufacturing issues while helping suppliers manage costs related to sustainment of mature products impacting your bottom line.

Contact Us

Micross Orlando
Die Distribution & Hermetic/Plastic Packaging
(Precision Die Attach & SiP Assembly)

Micross UK-Norwich
Die Distribution &
Specialty Packaging/Assembly

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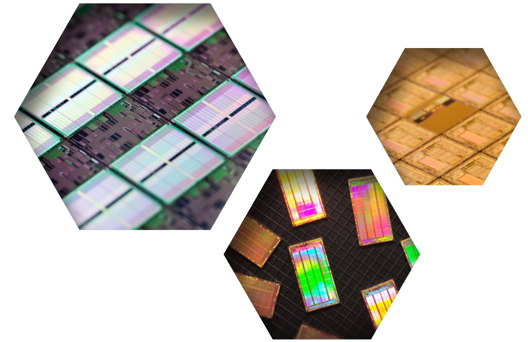
Leveraging our CAPABILITIES TO WORK for YOU

Die Storage & Services



- Procure & store supplier horizon EOL or volume die for sustainment
- Provide a seamless extended support model for our customers
- Extend the life of products for years after intended EOL
- Targeted capital investments for key customers & programs available
- Flexible inventory model to support key customers & programs

Taking EOL Die Solutions Further

Complete Packaging Capabilities

- Hermetic Packaging: Ceramic & Metal Can
- Wafer-level Vacuum/ Hermetic Packaging
- Plastic Packaging: CSP/ BGA/QFN
- Custom Packaging
- Flip-Chip/MCM/SiP
- Die Stacking 2.5D /3D

Extended Temperature (-55˚C to 125˚C)

- CSP (Chip Scale Package)
- BGA (Ball Grid Array)
- QFN (Quad Flat No-Leads)
- SiP (System in Package)

Services & Support

- Package Design
- Full Package Characterization Turnkey Assembly & Test
- Reliability Testing & Failure Analysis

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